

N-Channel and P-Channel Complementary MOSFET

Product Summary NMOS

- V_{DS} 40V
- I_D 39A
- $R_{DS(ON)}$ (at $V_{GS}=10V$) $<13m\Omega$
- $R_{DS(ON)}$ (at $V_{GS}=4.5V$) $<21m\Omega$

PMOS

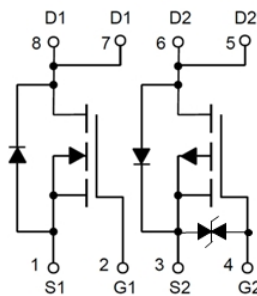
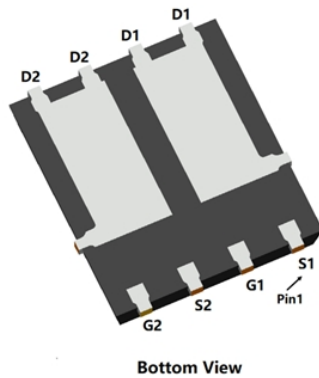
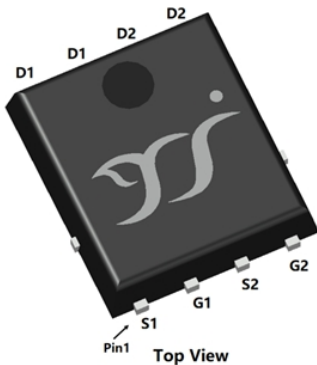
- V_{DS} -40V
- I_D -45A
- $R_{DS(ON)}$ (at $V_{GS}=-10V$) $<13m\Omega$
- $R_{DS(ON)}$ (at $V_{GS}=-4.5V$) $<20m\Omega$
- 100% EAS Tested
- 100% ∇V_{DS} Tested
- ESD Level(HBM) H1C

General Description

- Excellent package for heat dissipation
- High density cell design for low $R_{DS(ON)}$
- High Speed switching
- Moisture Sensitivity Level 1
- Epoxy Meets UL 94 V-0 Flammability Rating
- Halogen Free
- Part no. with suffix "Q" means AEC-Q101 qualified

Applications

- BMS
- Reverse polarity protection
- BLDC Motor driver
- Load switch



PDFN5060-8L

Limiting Values

Parameter	Conditions		Symbol	NMOS		PMOS		Unit
				Min	Max	Min	Max	
Drain-source Voltage			V_{DS}	-	40	-	-40	V
Gate-source Voltage (Note 1)			V_{GS}	-20	20	-20	20	
Continuous Drain Current (Note 2,3)	Steady-State	$T_A=25^\circ C$	I_D	-	9	-	-9.8	A
		$T_A=100^\circ C$		-	5.7	-	-6.2	
Continuous Drain Current (Note 2,4)	Steady-State	$T_C=25^\circ C$		-	39	-	-45	
		$T_C=100^\circ C$		-	24.6	-	-28.4	
Pulsed Drain Current	$T_C=25^\circ C, t_p \leq 10\mu s$		I_{DM}	-	156	-	-180	
Maximum Body-Diode Continuous Current	$T_C=25^\circ C$		I_S	-	32	-	-37	
Avalanche Energy (non-repetitive)	NMOS: $T_J=25^\circ C, V_G=10V, R_G=25\Omega, L=0.5mH, I_{AS}=14A$		EAS	-	49	-	110.2	mJ
	PMOS: $T_J=25^\circ C, V_G=-10V, R_G=25\Omega, L=0.5mH, I_{AS}=-21A$							
Total Power Dissipation (Note 2,3)	Steady-State	$T_A=25^\circ C$	P_D	-	2.01	-	2.08	W
		$T_A=100^\circ C$		-	0.8	-	0.83	
Total Power Dissipation (Note 2,4)	Steady-State	$T_C=25^\circ C$		-	37.8	-	44.6	
		$T_C=100^\circ C$		-	15.1	-	17.8	
Junction and Storage Temperature Range			T_J, T_{STG}	-55	150	-55	150	$^\circ C$

Thermal Resistance

Parameter		Symbol	NMOS		PMOS		Units
			Typ	Max	Typ	Max	
Thermal Resistance Junction-to-Ambient (Note 3)	Steady-State	$R_{\theta JA}$	-	62	-	60	$^\circ C/W$
Thermal Resistance Junction-to-Case	Steady-State	$R_{\theta JC}$	-	3.3	-	2.8	



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■ NMOS Electrical Characteristics

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A, T_j=25^\circ C$	40	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=40V, V_{GS}=0V, T_j=25^\circ C$	-	-	1	μA
		$V_{DS}=40V, V_{GS}=0V, T_j=125^\circ C$	-	-	100	
Gate-Source Leakage Current	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V, T_j=25^\circ C$	-	-	± 100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A, T_j=25^\circ C$	1	1.5	2	V
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=20A, T_j=25^\circ C$	-	10.5	13	m Ω
		$V_{GS}=4.5V, I_D=10A, T_j=25^\circ C$	-	14	21	
Diode Forward Voltage	V_{SD}	$I_S=20A, V_{GS}=0V, T_j=25^\circ C$	-	0.89	1.2	V
Gate Resistance	R_G	$f=1MHz, T_j=25^\circ C$	-	2.6	-	Ω
Dynamic Parameters						
Input Capacitance	C_{ISS}	$V_{DS}=20V, V_{GS}=0V, f=1MHz, T_j=25^\circ C$	-	1012	1518	pF
Output Capacitance	C_{OSS}		-	126	-	
Reverse Transfer Capacitance	C_{RSS}		-	98	-	
Switching Parameters						
Total Gate Charge	Q_g	$V_{GS}=10V, V_{DS}=20V, I_D=20A, T_j=25^\circ C$	-	21.5	-	nC
Gate-Source Charge	Q_{gs}		-	3.3	-	
Gate-Drain Charge	Q_{gd}		-	4.9	-	
Reverse Recovery Charge	Q_{rr}	$I_F=20A, di/dt=100A/\mu s, V_{GS}=0V, V_R=20V, T_j=25^\circ C$	-	7	-	nC
Reverse Recovery Time	t_{rr}		-	13	-	ns
Turn-on Delay Time	$t_{D(on)}$	$V_{GS}=10V, V_{DS}=20V, I_D=20A, R_{GEN}=3\Omega, T_j=25^\circ C$	-	7.6	-	ns
Turn-on Rise Time	t_r		-	3.8	-	
Turn-off Delay Time	$t_{D(off)}$		-	25.6	-	
Turn-off Fall Time	t_f		-	5.9	-	



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PMOS Electrical Characteristics

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=-250\mu A, T_j=25^\circ C$	-40	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=-40V, V_{GS}=0V, T_j=25^\circ C$	-	-	-1	μA
		$V_{DS}=-40V, V_{GS}=0V, T_j=125^\circ C$	-	-	-100	
Gate-Source Leakage Current	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V, T_j=25^\circ C$	-	-	± 10	μA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=-250\mu A, T_j=25^\circ C$	-1.2	-1.7	-2.2	V
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=-10V, I_D=-20A, T_j=25^\circ C$	-	9.8	13	m Ω
		$V_{GS}=-4.5V, I_D=-10A, T_j=25^\circ C$	-	13.4	20	
Diode Forward Voltage	V_{SD}	$I_S=-20A, V_{GS}=0V, T_j=25^\circ C$	-	-0.9	-1.2	V
Gate Resistance	R_G	$f=1MHz, T_j=25^\circ C$	-	6.5	-	Ω
Dynamic Parameters						
Input Capacitance	C_{iss}	$V_{DS}=-20V, V_{GS}=0V, f=1MHz, T_j=25^\circ C$	-	3006	4509	μF
Output Capacitance	C_{oss}		-	324	-	
Reverse Transfer Capacitance	C_{rss}		-	268	-	
Switching Parameters						
Total Gate Charge	Q_g	$V_{GS}=-10V, V_{DS}=-20V, I_D=-20A, T_j=25^\circ C$	-	55.4	-	nC
Gate-Source Charge	Q_{gs}		-	10.2	-	
Gate-Drain Charge	Q_{gd}		-	9.8	-	
Reverse Recovery Charge	Q_{rr}	$I_F=-20A, di/dt=100A/\mu s, V_{GS}=0V, V_R=-20V, T_j=25^\circ C$	-	24.7	-	nC
Reverse Recovery Time	t_{rr}		-	24.7	-	ns
Turn-on Delay Time	$t_{D(on)}$	$V_{GS}=-10V, V_{DS}=-20V, I_D=-20A, R_{GEN}=3\Omega, T_j=25^\circ C$	-	10.6	-	ns
Turn-on Rise Time	t_r		-	63.9	-	
Turn-off Delay Time	$t_{D(off)}$		-	95.1	-	
Turn-off Fall Time	t_f		-	66.5	-	

Note:

1. PMOS: $V_{GS}=-20V/+10V$ according AEC-Q101 at $T_j=150^\circ C$.
2. The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
3. The value of $R_{\theta JA}$ is measured with the device mounted on the 40mm*40mm*1.1mm single layer FR-4 PCB board with 1 in² pad of 2oz. Copper, in the still air environment with $T_A=25^\circ C$. The maximum allowed junction temperature of 150 $^\circ C$. The value in any given application depends on the user's specific board design.
4. Thermal resistance from junction to soldering point (on the exposed drain pad).



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■ NMOS Typical Electrical and Thermal Characteristics Diagrams

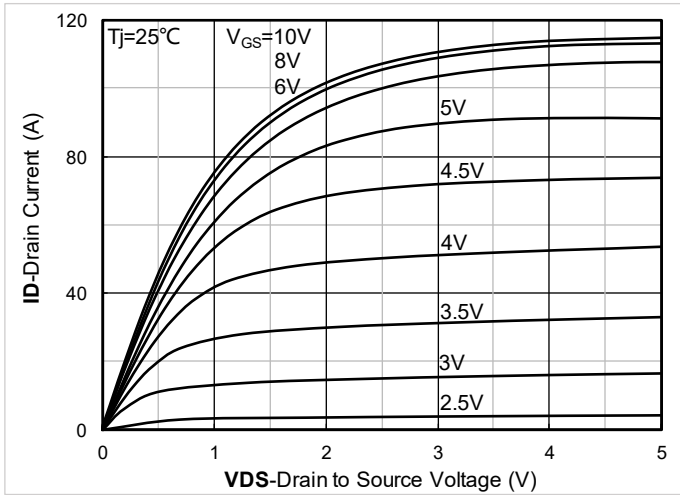


Figure 1. Output Characteristics; typical values

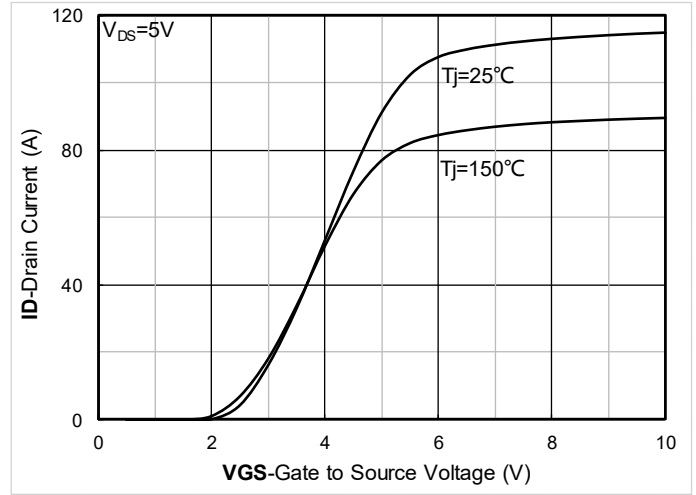


Figure 2. Transfer Characteristics; typical values

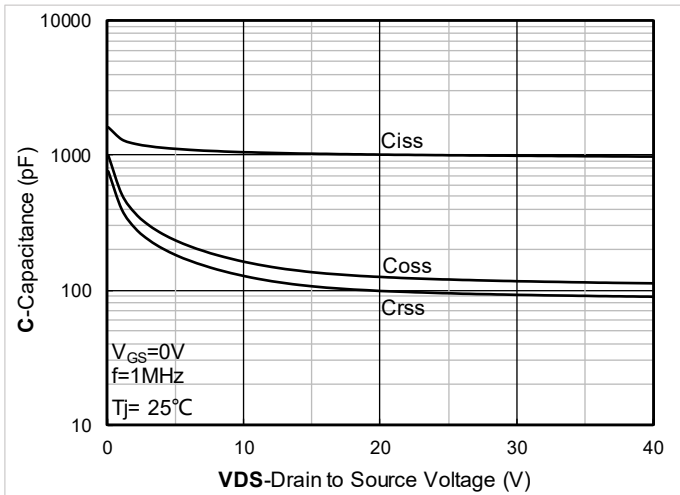


Figure 3. Capacitance Characteristics; typical values

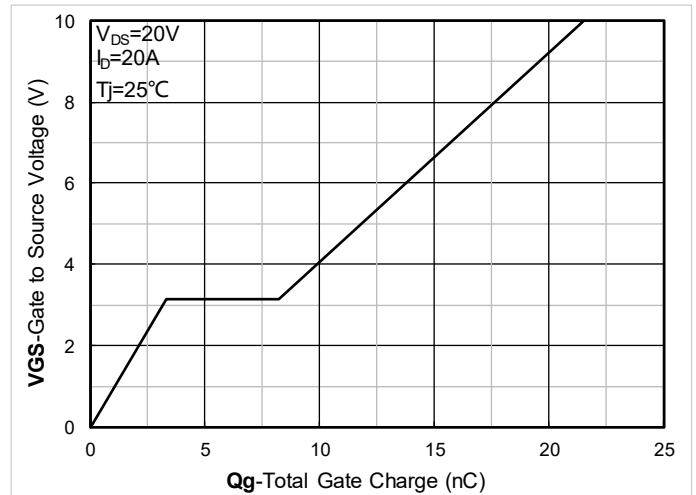


Figure 4. Gate Charge; typical values

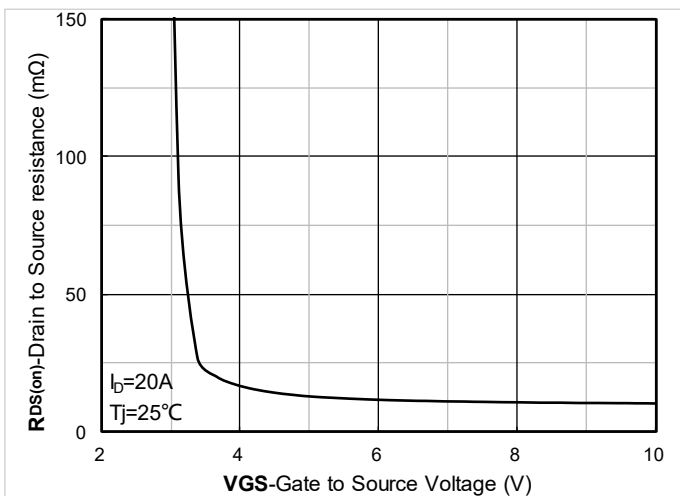


Figure 5. On-Resistance vs. Gate to Source Voltage; typical values

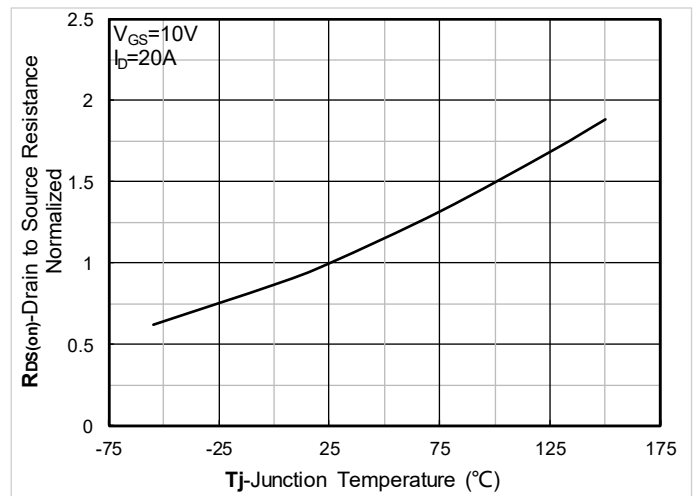


Figure 6. Normalized On-Resistance



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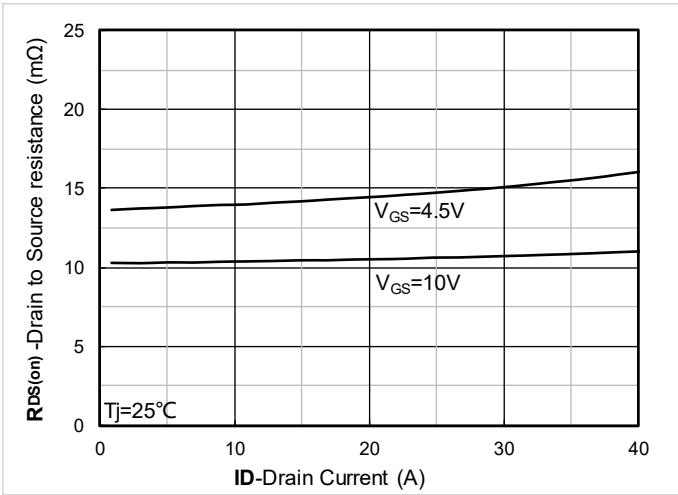


Figure 7. $R_{DS(on)}$ vs. Drain Current; typical values

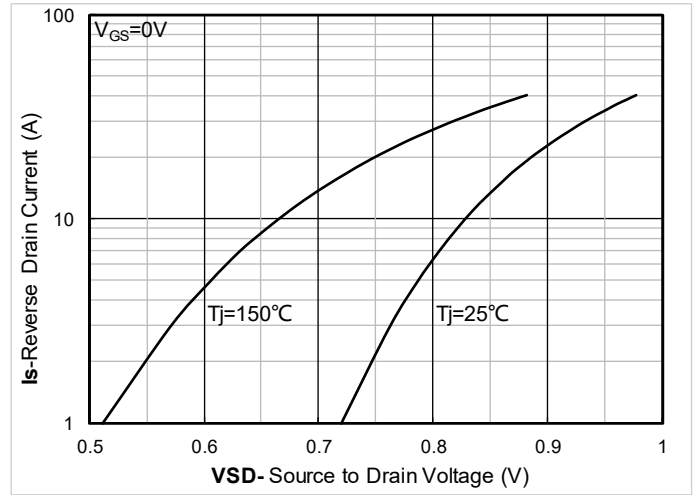


Figure 8. Forward characteristics of reverse diode; typical values

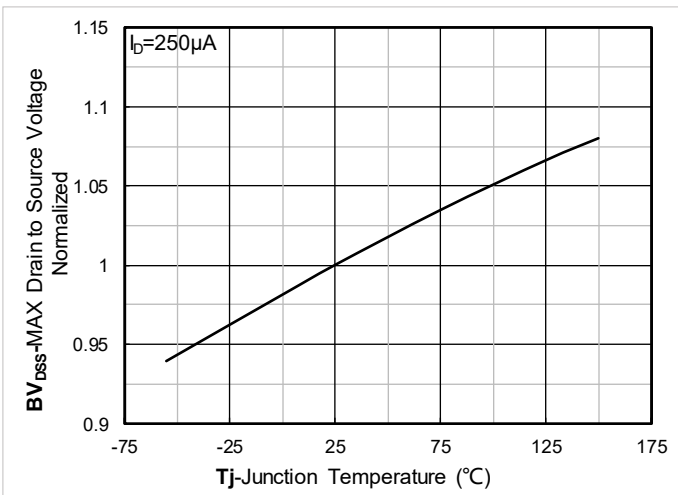


Figure 9. Normalized breakdown voltage

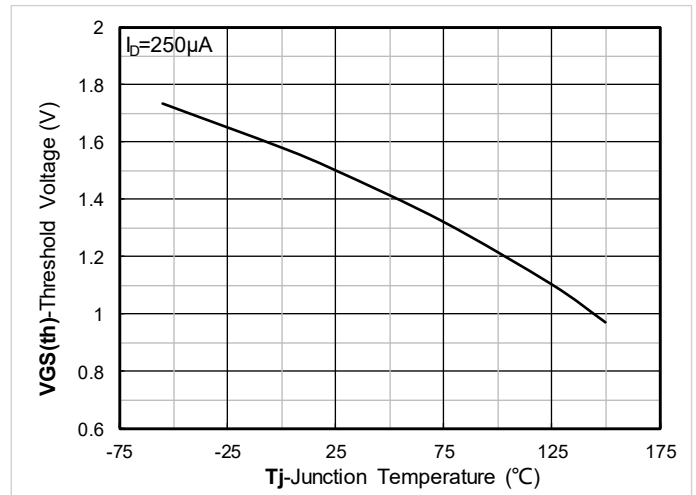


Figure 10. Gate Threshold voltage; typical values

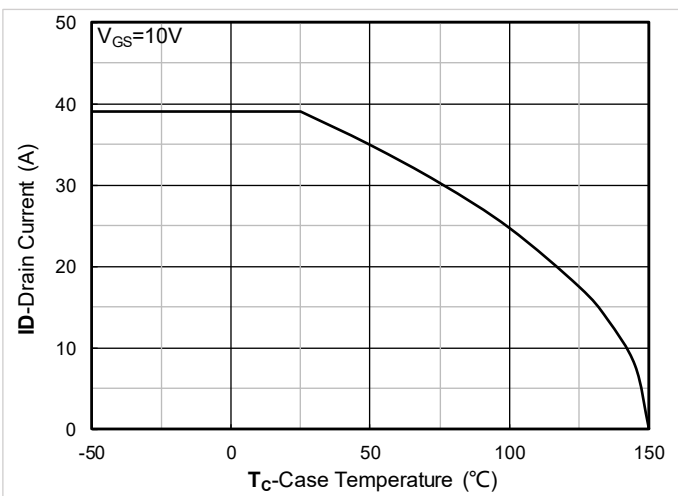


Figure 11. Current dissipation

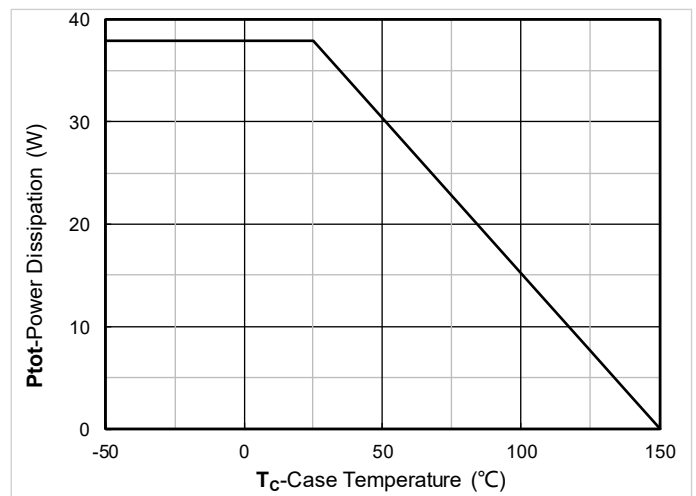


Figure 12. Power dissipation

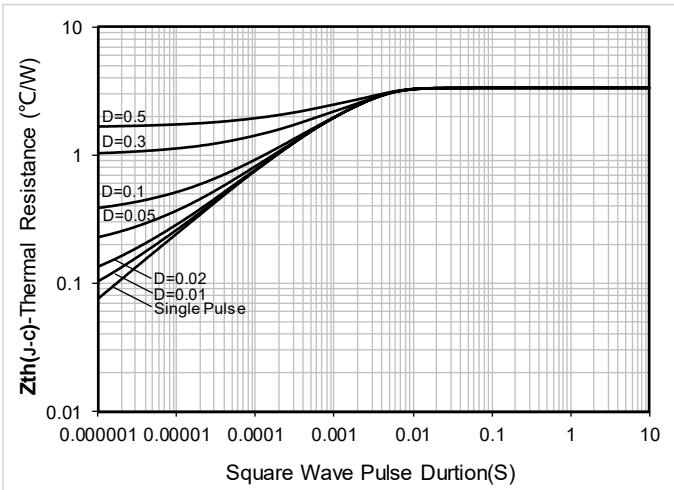


Figure 13. Maximum Transient Thermal Impedance

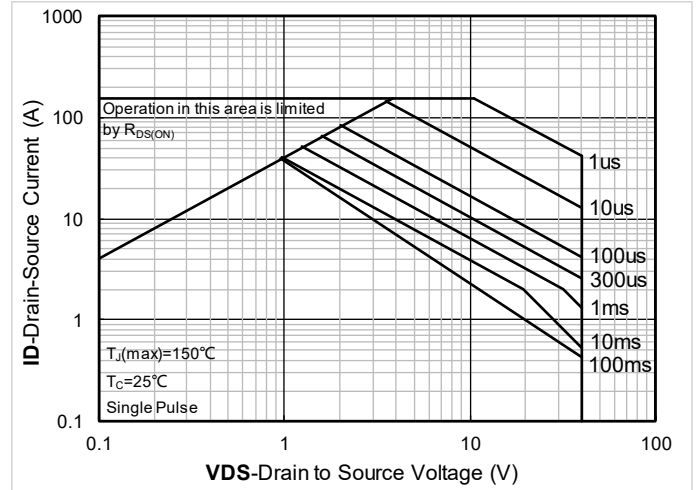


Figure 14. Safe Operation Area

PMOS Typical Electrical and Thermal Characteristics Diagrams

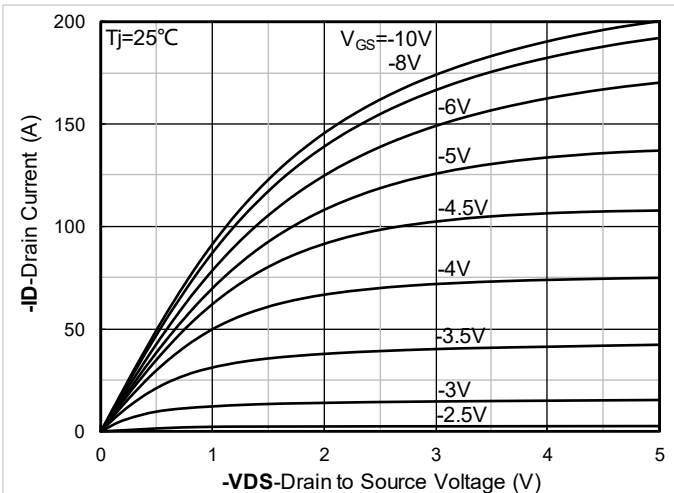


Figure 1. Output Characteristics; typical values

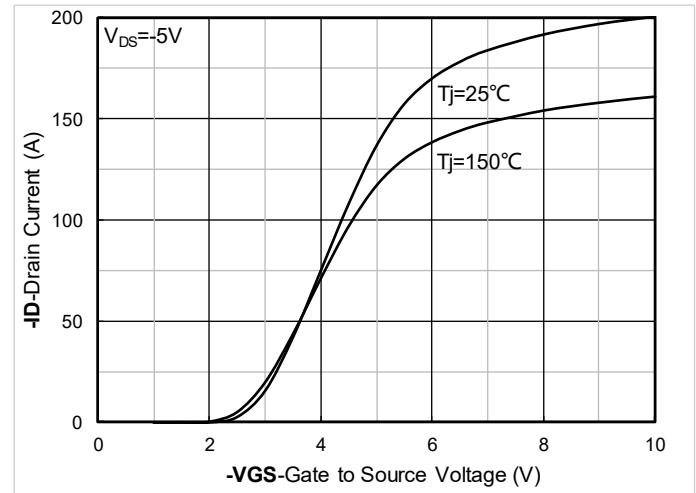


Figure 2. Transfer Characteristics; typical values

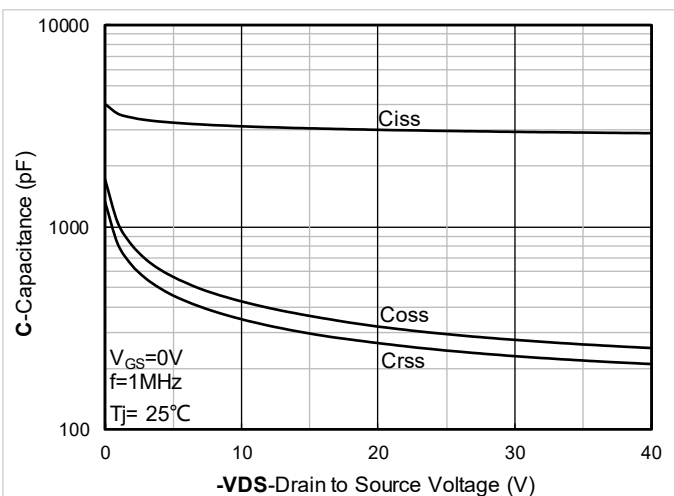


Figure 3. Capacitance Characteristics; typical values

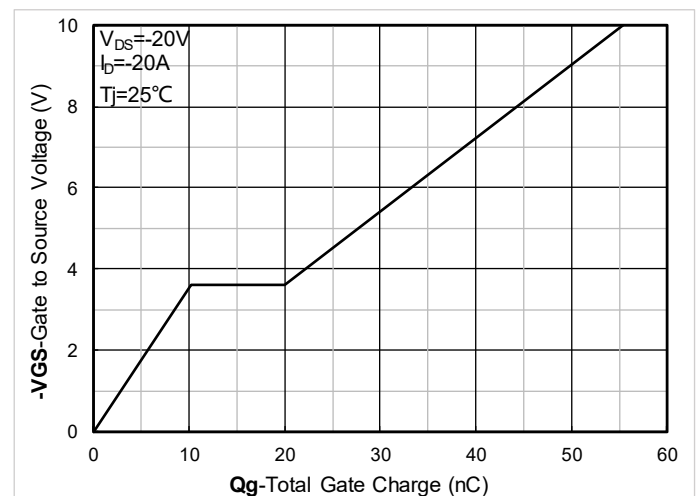


Figure 4. Gate Charge; typical values



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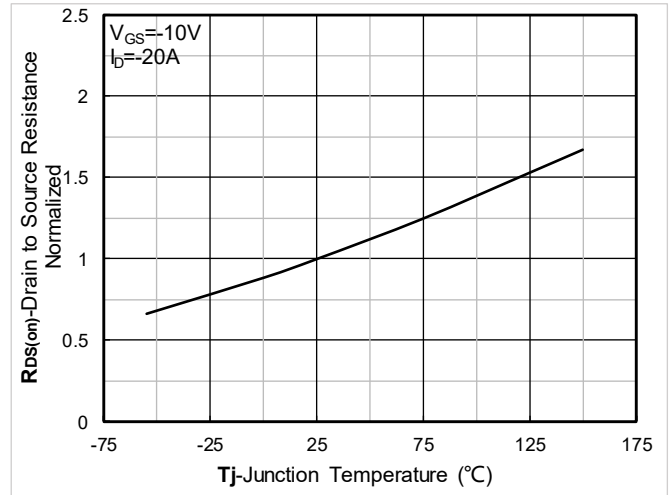
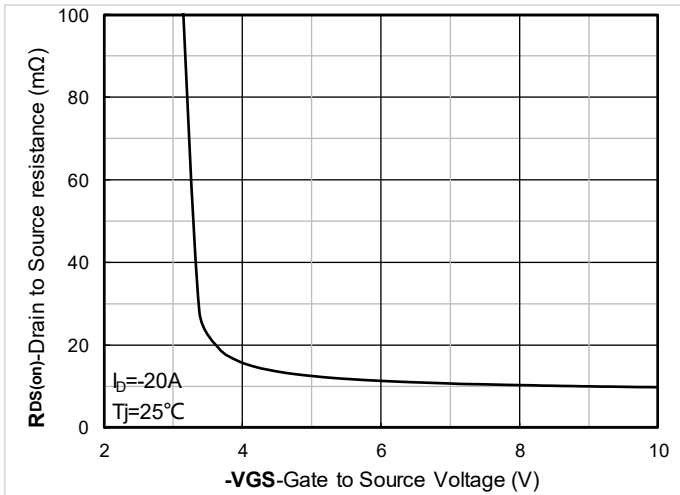


Figure 5. On-Resistance vs. Gate to Source Voltage; typical values

Figure 6. Normalized On-Resistance

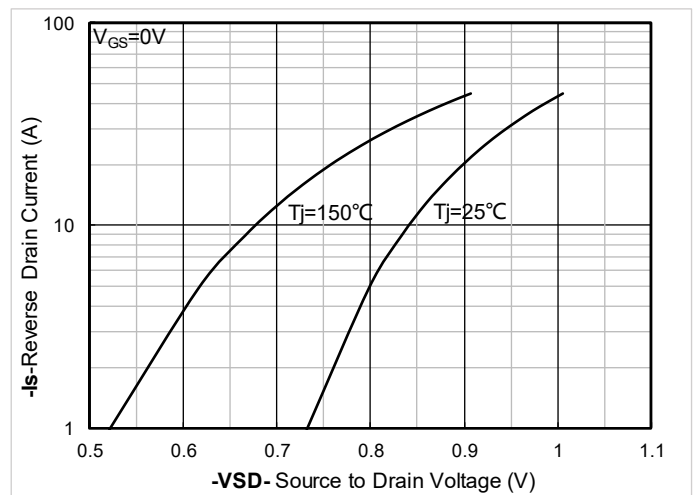
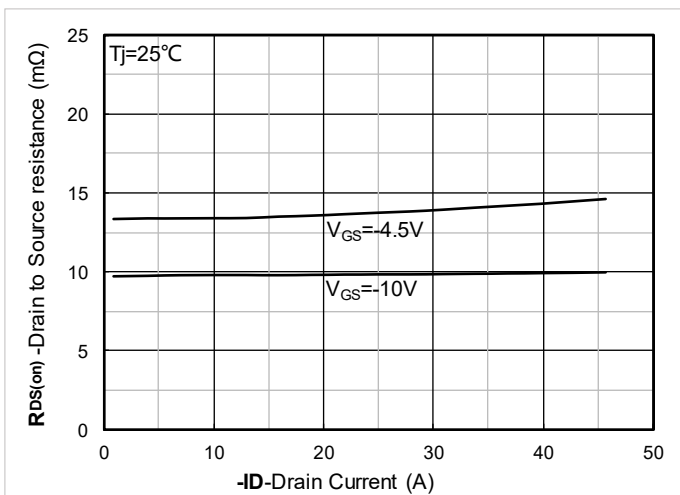


Figure 7. RDS(on) vs. Drain Current; typical values

Figure 8. Forward characteristics of reverse diode; typical values

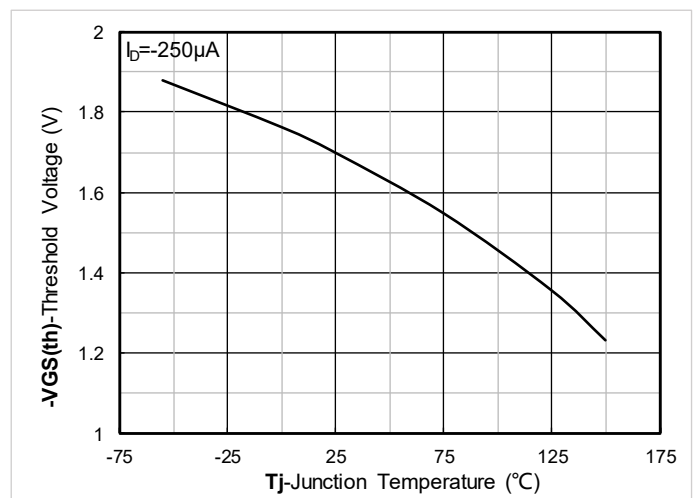
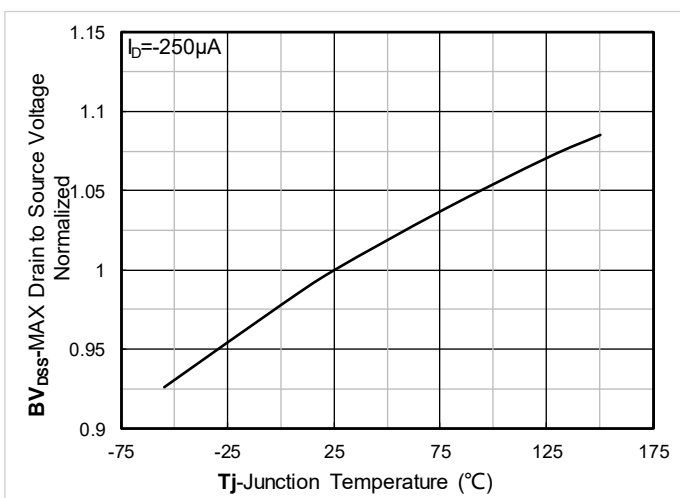


Figure 9. Normalized breakdown voltage

Figure 10. Gate Threshold voltage; typical values



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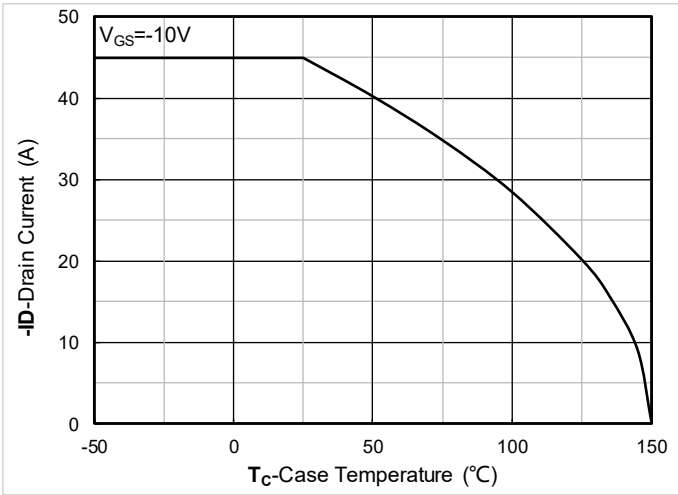


Figure 11. Current dissipation

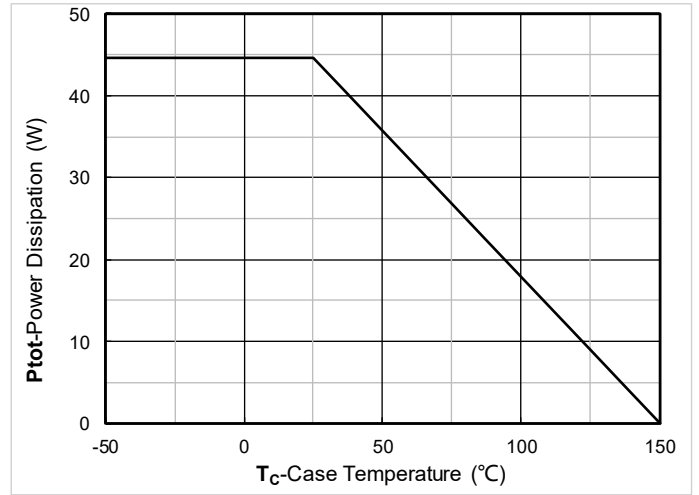


Figure 12. Power dissipation

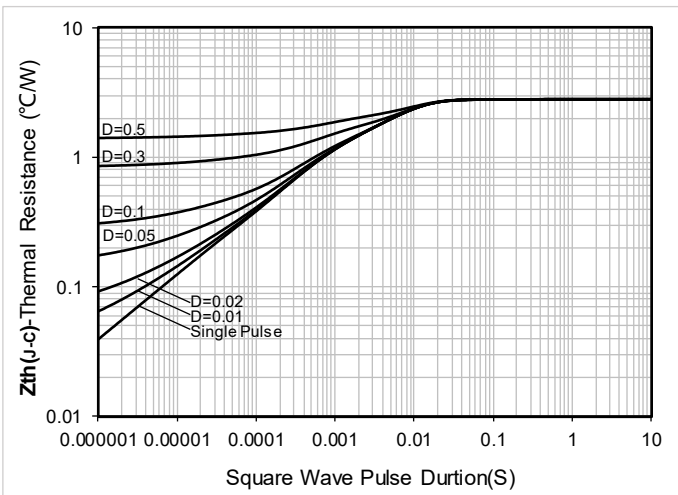


Figure 13. Maximum Transient Thermal Impedance

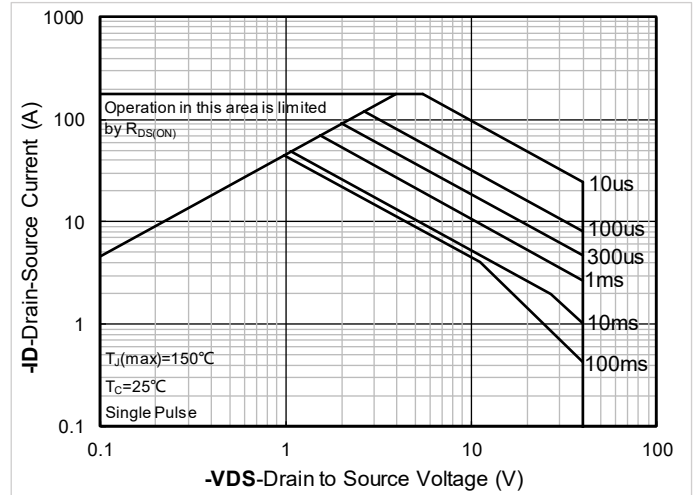
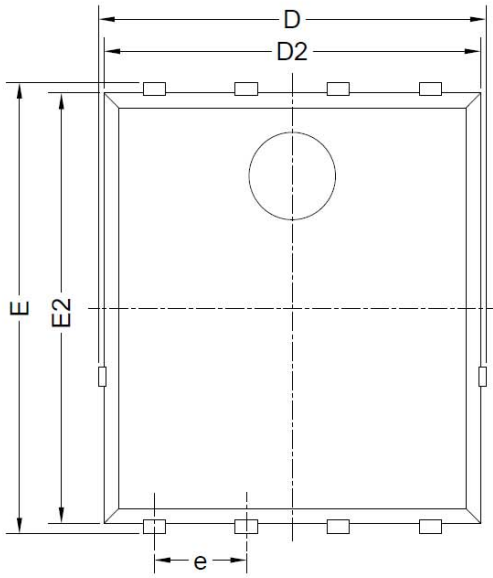


Figure 14. Safe Operation Area

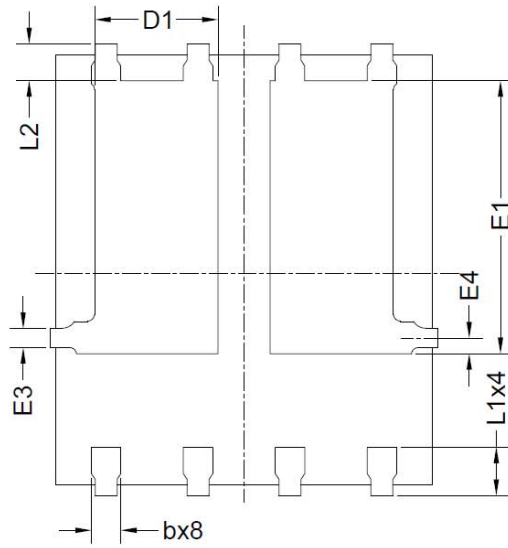


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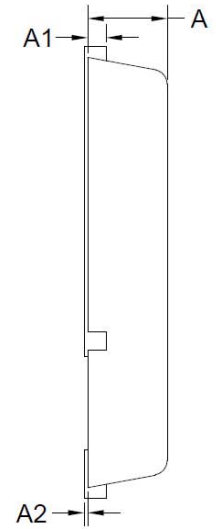
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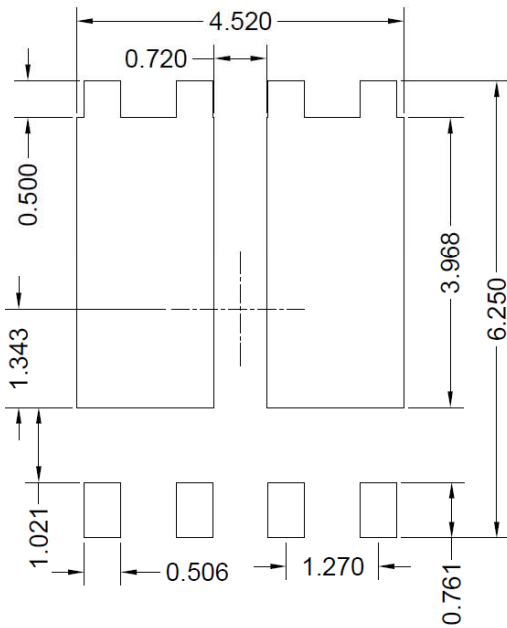
Top View
正面视图



Bottom View
背面视图



Side View
侧面视图



Suggested Solder Pad Layout
Top View

SYMBOL	MILLIMETER		
	MIN	NOM	MAX
D	5.15	5.35	5.55
E	5.95	6.15	6.35
A	1.00	1.10	1.20
A1	0.254 BSC		
A2			0.10
D1	1.50	1.70	1.90
E1	3.52	3.72	3.92
D2	5.00	5.20	5.40
E2	5.66	5.86	6.06
E3	0.254REF		
E4	0.21REF		
L1	0.56	0.66	0.76
L2	0.50 BSC		
b	0.31	0.41	0.51
e	1.27 BSC		

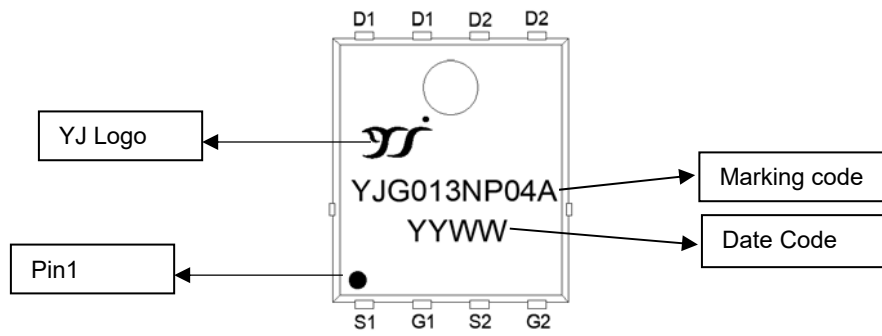
Note:

1. Controlling dimension: in millimeters.
2. General tolerance: ± 0.10 mm.
3. The pad layout is for reference purposes only.



YJG013NP04AHQ

■ Marking Information



Note:

1. All marking is at middle of the product body
2. All marking is in laser printing
3. YJG013NP04A is part no., YYWW is date code, "YY" is year, "WW" is week
4. Body color: Black



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Disclaimer

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